

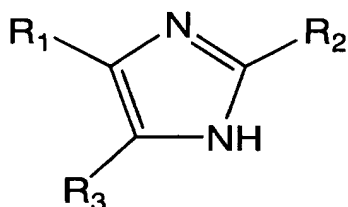
AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions of claims in the application.

1. (Previously presented): A polishing slurry for metal, comprising an oxidizer, a metal oxide dissolving agent, a metal inhibitor, and water, wherein the metal inhibitor comprises:

a compound having an amino-triazole skeleton wherein an amino group is bonded to carbon in a triazole ring; and

a compound having an imidazole skeleton and represented by the following general formula (I):



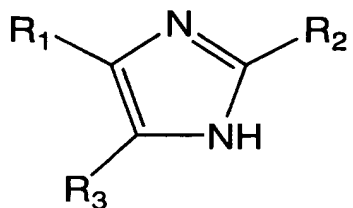
(I)

wherein R₁, R₂ and R₃ each independently represent a hydrogen atom, an amino group, or a C₁-C₁₂ alkyl chain provided that the case that all of R₁, R₂ and R₃ are hydrogen atoms is excluded.

2. (Withdrawn): A polishing slurry for metal, comprising an oxidizer, a metal oxide dissolving agent, a metal inhibitor, and water, wherein the metal inhibitor comprises:

a compound having a triazole skeleton having no amino group; and

a compound having an imidazole skeleton and represented by the following general formula (I):



(I)

wherein R₁, R₂ and R₃ each independently represent a hydrogen atom, an amino group, or a C₁-C₁₂ alkyl chain provided that the case that all of R₁, R₂ and R₃ are hydrogen atoms is excluded.

3. (Withdrawn): A polishing slurry for metal, comprising an oxidizer, a metal oxide dissolving agent, a metal inhibitor, and water, wherein the metal inhibitor comprises:

a compound having an amino-triazole skeleton wherein an amino group is bonded to carbon in a triazole ring; and

a compound having a triazole skeleton having no amino group.

4. (Previously presented): The polishing slurry according to claim 1 or 3, wherein the compound having the amino-triazole skeleton is 3-amino-1,2,4-triazole.

5. (Previously presented): The polishing slurry according to claim 1 or 2, wherein the compound having the imidazole skeleton is at least one selected from the group consisting of 2-methylimidazole, 2-ethylimidazole, 2-(isopropyl)imidazole, 2-propylimidazole, 2-butylimidazole, 4-methylimidazole, 2,4-dimethylimidazole, and 2-ethyl-4-methylimidazole.

6. (Withdrawn): The polishing slurry according to claim 2 or 3, wherein the compound having the triazole skeleton having no amino group is at least one selected from the group consisting of 1,2,3-triazole, 1,2,4-triazole, benzotriazole, and 1-hydroxybenzotriazole.

7. (Currently Amended): The polishing slurry according to ~~any one of claims 1 to 3~~ claim 1, wherein the metal inhibitor comprises the compound having the amino-triazole skeleton, ~~the a~~ a compound having the triazole skeleton having no amino group, and the compound having the imidazole skeleton.

8. (Previously presented): The polishing slurry for metal according to any one of claims 1 to 3, further comprising a water-soluble polymer.

9. (Previously presented): The polishing slurry for metal according to claim 8, wherein the water-soluble polymer is at least one selected from polysaccharides, polycarboxylic acids, polycarboxylic acid esters, polycarboxylic acid salts, polyacrylamide, and vinyl polymers.

10. (Previously presented): The polishing slurry for metal according to any one of claims 1 to 3, wherein the oxidizer for metal is at least one selected from the group consisting of hydrogen peroxide, nitric acid, potassium periodate, hypochlorous acid, persulfates, and ozone water.

11. (Previously presented): The polishing slurry for metal according to any one of claims 1 to 3, wherein the metal oxide dissolving agent is at least one selected from the group consisting of organic acids, organic acid esters, ammonium salts of organic acids, and sulfuric acid.

12. (Previously presented): The polishing slurry for metal according to any one of claims 1 to 3, further comprising an abrasive.

13. (Currently Amended): The polishing slurry for metal according to any one of claims 1 to 3, wherein ~~a metal film to be polished is~~ said slurry is capable of polishing at least one metal selected from the group consisting of copper, copper alloys, copper oxides, oxides of copper

alloys, tantalum and compounds thereof, titanium and compounds thereof, and tungsten and compounds thereof.

14. (Withdrawn): A method for polishing a metal film by supplying the polishing slurry for metal according to any one of claims 1 to 3 onto a polishing cloth of a polishing table while moving the polishing table and a substrate having the metal film relatively in the state that the substrate is pressed against the polishing cloth.

15. (Withdrawn): The polishing method according to claim 14, wherein the metal film is at least one selected from the group consisting of copper, copper alloys, copper oxides, oxides of copper alloys, tantalum and compounds thereof, titanium and compounds thereof, and tungsten and compounds thereof.

16. (Withdrawn): The polishing method according to claim 14, wherein a laminate of two or more metal films is continuously polished.

17. (Withdrawn): The polishing method according to claim 16, wherein a first film which is first polished among the two or more metal laminated films is one or more selected from copper, copper alloys, copper oxides, and oxides of copper alloys, and a second film which is next polished among them is one or more selected from tantalum and compounds thereof, titanium and compounds thereof, and tungsten and compounds thereof.

18. (Withdrawn): A polishing method, comprising a first polishing step of polishing a wiring metal layer of a substrate, the substrate comprising an interlayer insulating film which has a surface consisting of concave portions and convex portions, a barrier layer which covers the interlayer insulating film along the surface thereof, and a wiring metal layer which fills the

concave portions to cover the barrier layer, and thereby making the barrier layer at the convex portions exposed, and a second polishing step of polishing at least the barrier layer and the wiring metal layer at the concave portions after the first polishing step, thereby making the interlayer insulating layer at the convex portions exposed, wherein the polishing is performed by use of the polishing slurry for metal according to any one of claims 1 to 3 at least in the second polishing step.

19. Cancelled.

20. Cancelled.